

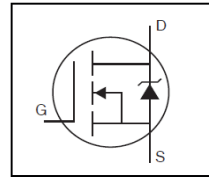
HEXFET® Power MOSFET

**Features**

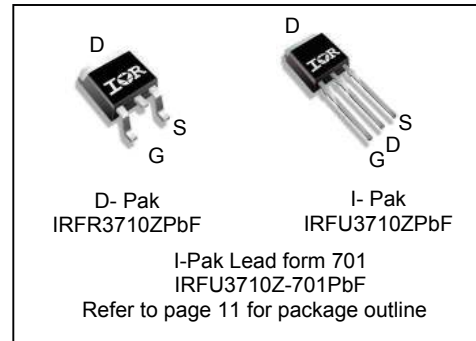
- Advanced Process Technology
- Ultra Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to  $T_{jmax}$
- Multiple Package Options
- Lead-Free

**Description**

This HEXFET® Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in a wide variety of applications.



$V_{DSS}$	<b>100V</b>
$R_{DS(on)}$	<b>18mΩ</b>
$I_D$	<b>42A</b>



<b>G</b>	<b>D</b>	<b>S</b>
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IRFU3710ZPbF	I-Pak	Tube	75	IRFU3710ZPbF
IRFR3710ZPbF	D-Pak	Tube	75	IRFR3710ZPbF
		Tape and Reel Left	3000	IRFR3710ZTRLpbF

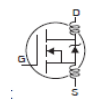
**Absolute Maximum Ratings**

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)	56	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	39	
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Package Limited)	42	
$I_{DM}$	Pulsed Drain Current ①	220	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	140	W
	Linear Derating Factor	0.95	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 20	V
$E_{AS}$ (Thermally limited)	Single Pulse Avalanche Energy ②	150	mJ
$E_{AS}$ (Tested)	Single Pulse Avalanche Energy Tested Value ⑥	200	
$I_{AR}$	Avalanche Current ①	See Fig.12a, 12b, 15, 16	A
$E_{AR}$	Repetitive Avalanche Energy ⑤		mJ
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

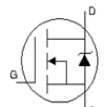
**Thermal Resistance**

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	1.05	°C/W
$R_{\theta JA}$	Junction-to-Ambient ( PCB Mount ) ⑦	—	50	
$R_{\theta JA}$	Junction-to-Ambient	—	110	

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

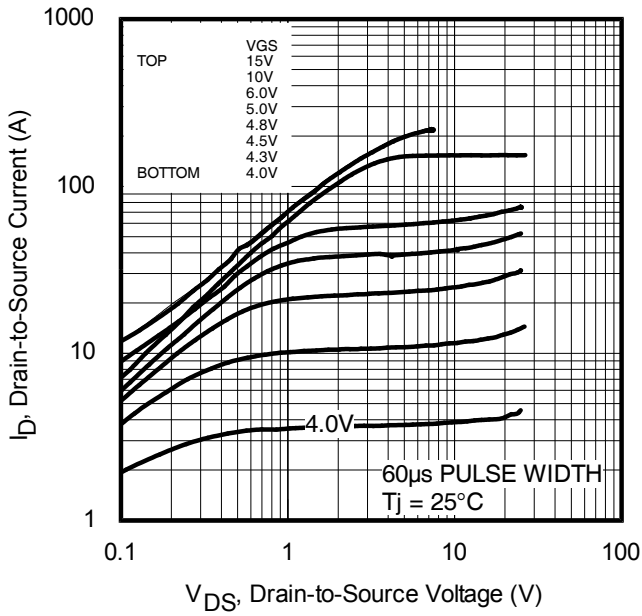
	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	100	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	—	0.088	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	15	18	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 33A ③
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	Forward Trans conductance	39	—	—	S	V <sub>DS</sub> = 25V, I <sub>D</sub> = 33A
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	20	μA	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	200	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Reverse Leakage	—	—	-200		V <sub>GS</sub> = -20V
Q <sub>g</sub>	Total Gate Charge	—	69	100	nC	I <sub>D</sub> = 33A
Q <sub>gs</sub>	Gate-to-Source Charge	—	15	—		V <sub>DS</sub> = 80V
Q <sub>gd</sub>	Gate-to-Drain ('Miller') Charge	—	25	—		V <sub>GS</sub> = 10V ③
t <sub>d(on)</sub>	Turn-On Delay Time	—	14	—	ns	V <sub>DD</sub> = 50V
t <sub>r</sub>	Rise Time	—	43	—		I <sub>D</sub> = 33A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	53	—		R <sub>G</sub> = 6.8Ω
t <sub>f</sub>	Fall Time	—	42	—		V <sub>GS</sub> = 10V ③
L <sub>D</sub>	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact 
L <sub>S</sub>	Internal Source Inductance	—	7.5	—		
C <sub>iss</sub>	Input Capacitance	—	2930	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	290	—		V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	180	—		f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	1200	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1.0V, f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	180	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 80V, f = 1.0MHz
C <sub>oss eff.</sub>	Effective Output Capacitance	—	430	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V to 80V

**Source-Drain Ratings and Characteristics**

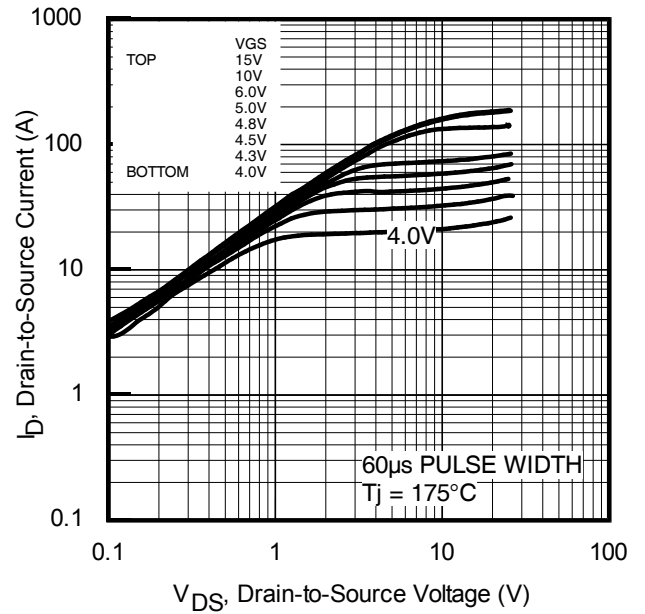
	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	56	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	220		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.3	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 33A, V <sub>GS</sub> = 0V ③
t <sub>rr</sub>	Reverse Recovery Time	—	35	53	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 33A, V <sub>DS</sub> = 50V
Q <sub>rr</sub>	Reverse Recovery Charge	—	41	62	nC	di/dt = 100A/μs ③
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				

**Notes:**

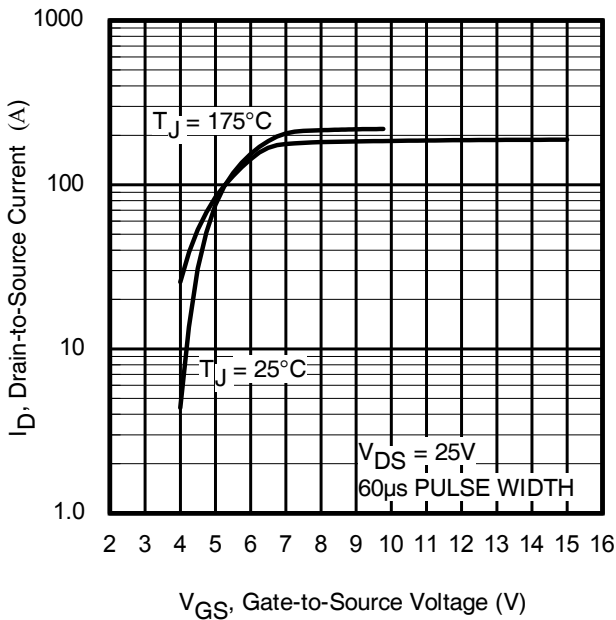
- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- ② starting T<sub>J</sub> = 25°C, L = 0.28mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 33A, V<sub>GS</sub> = 10V. Part not recommended for use above this value.
- ③ Pulse width ≤ 1.0ms; duty cycle ≤ 2%.
- ④ C<sub>oss eff.</sub> is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 to 80% V<sub>DSS</sub>
- ⑤ Limited by T<sub>Jmax</sub>, see Fig.12a, 12b, 15, 16 for typical repetitive avalanche performance.
- ⑥ This value determined from sample failure population. 100% tested to this value in production.
- ⑦ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑧ Refer to D-Pak package for Part Marking, Tape and Reel information



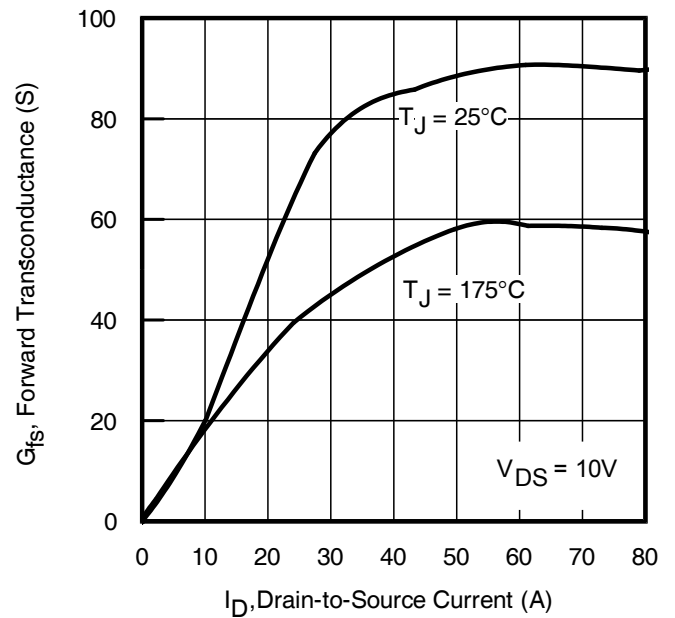
**Fig. 1** Typical Output Characteristics



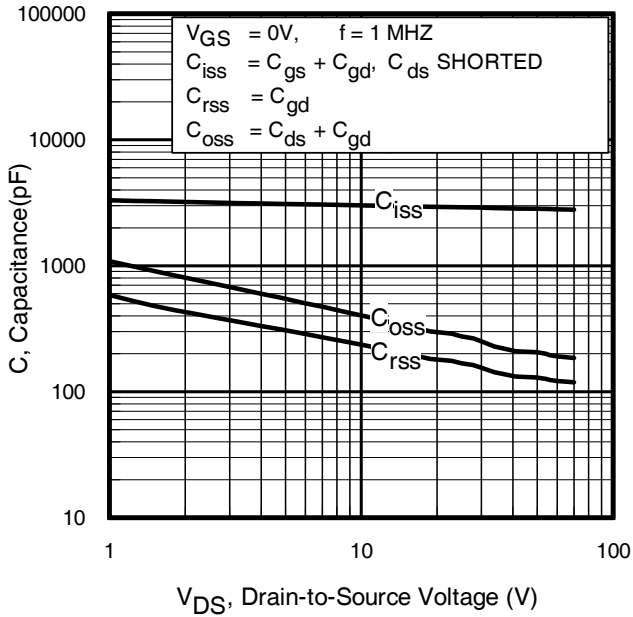
**Fig. 2** Typical Output Characteristics



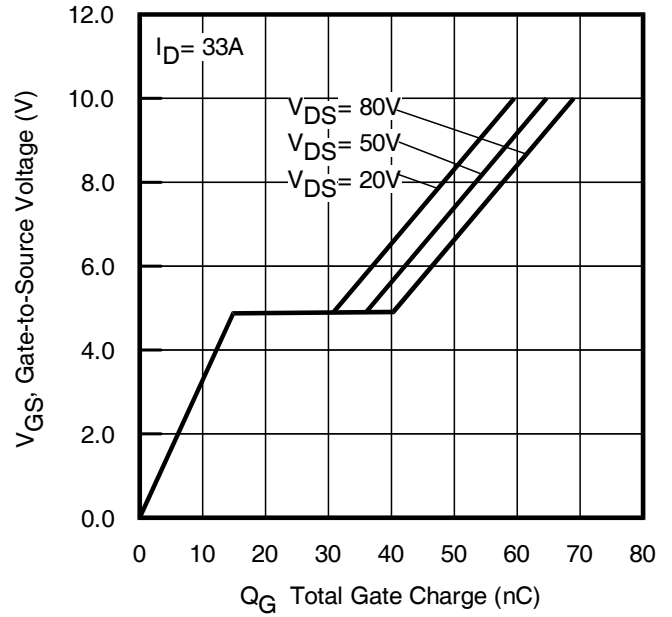
**Fig. 3** Typical Transfer Characteristics



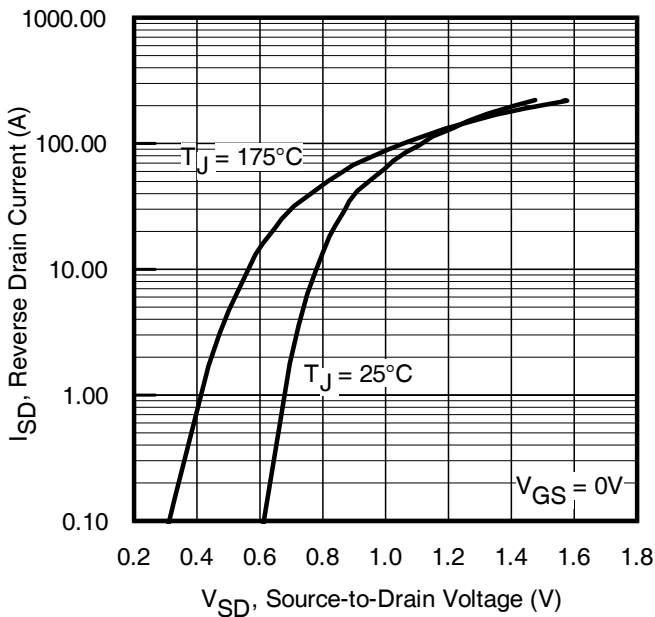
**Fig. 4** Typical Forward Transconductance vs. Drain Current



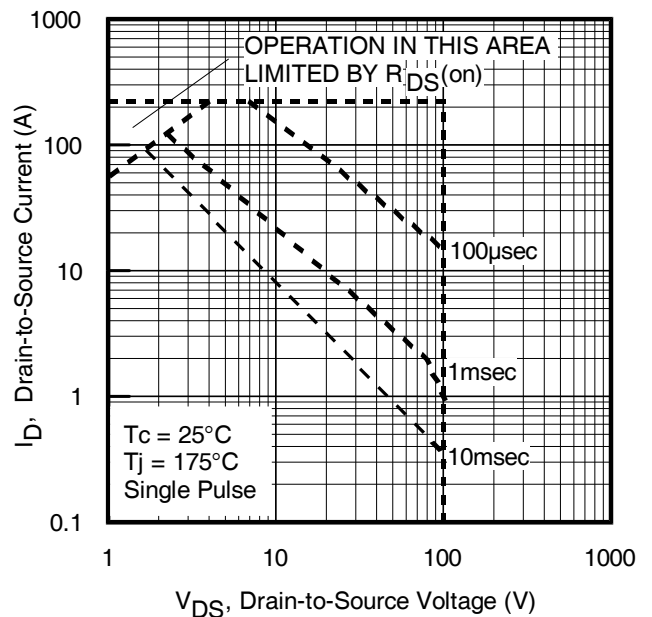
**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage



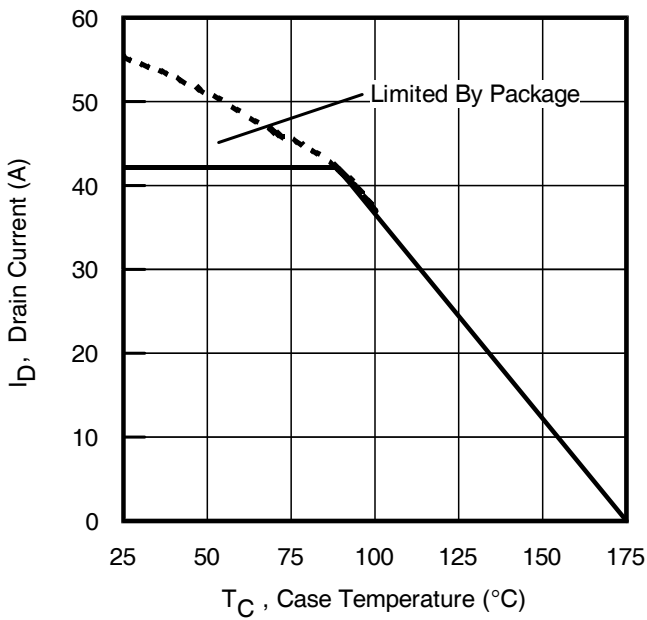
**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage



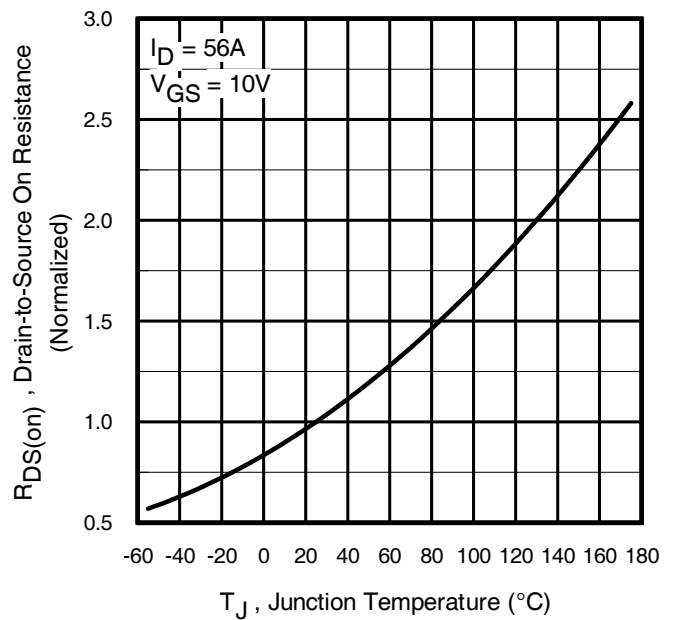
**Fig 7.** Typical Source-to-Drain Diode Forward Voltage



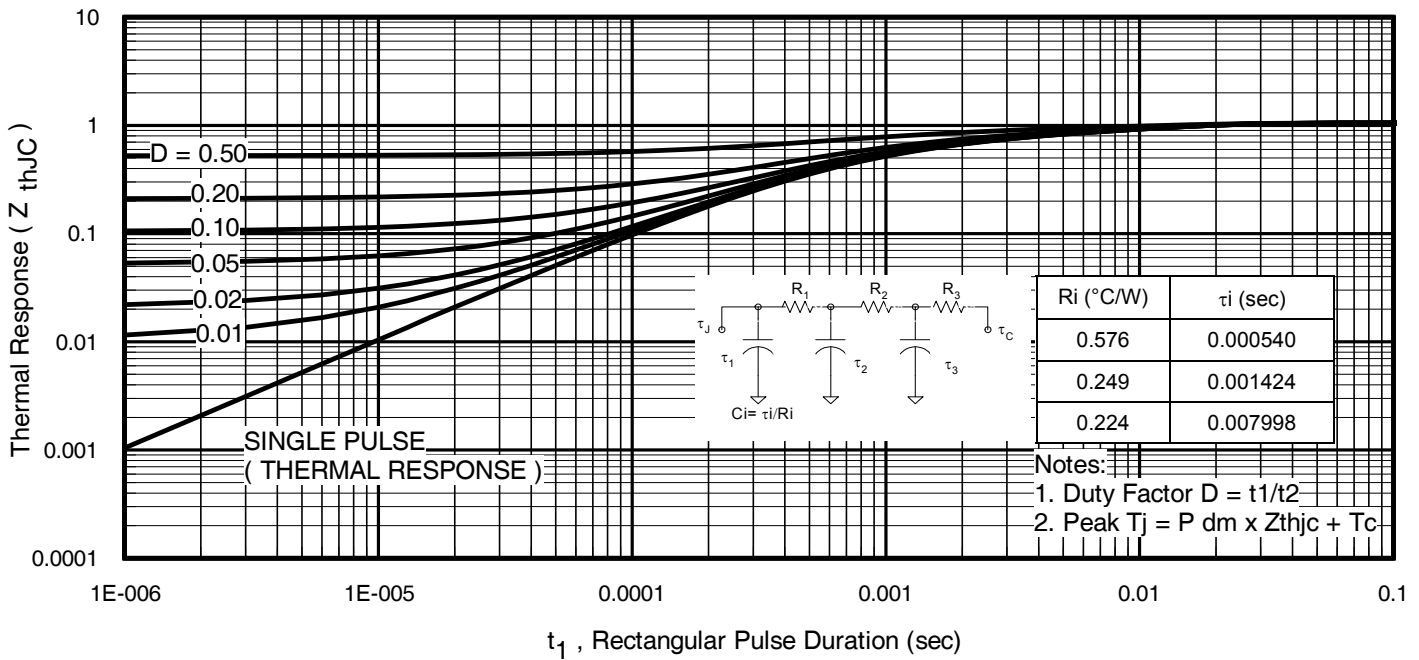
**Fig 8.** Maximum Safe Operating Area



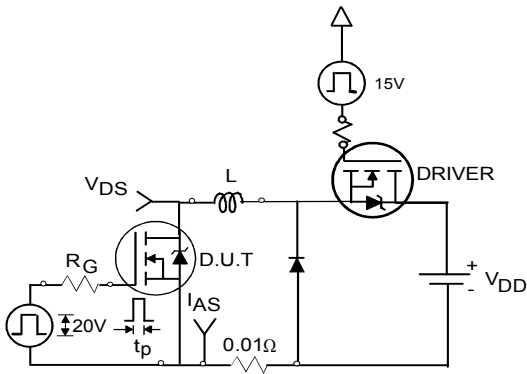
**Fig 9.** Maximum Drain Current vs. Case Temperature



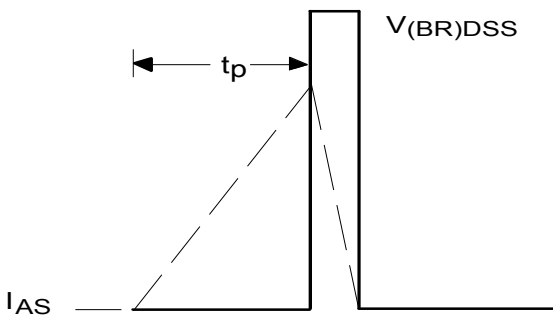
**Fig 10.** Normalized On-Resistance vs. Temperature



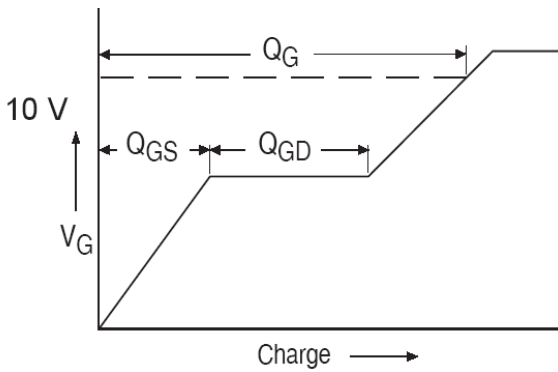
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



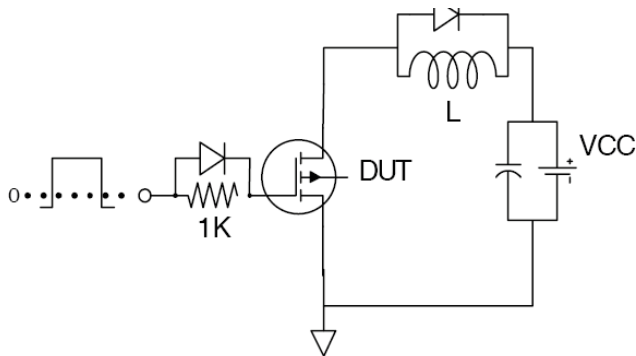
**Fig 12a.** Unclamped Inductive Test Circuit



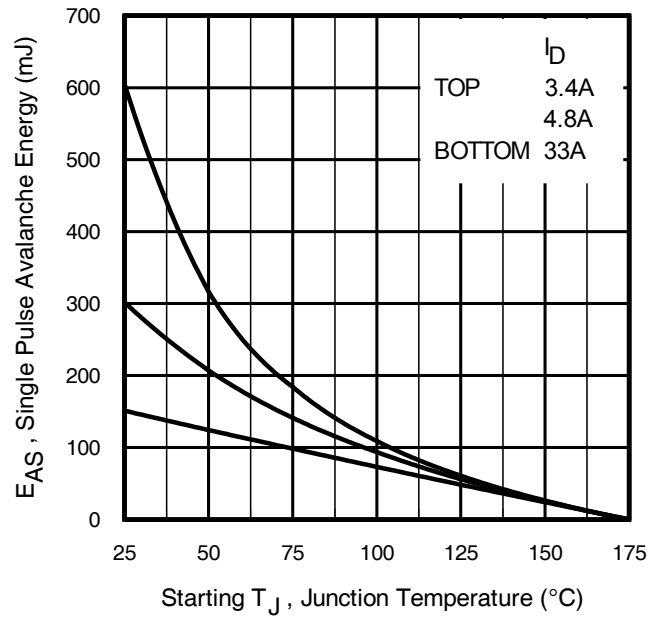
**Fig 12b.** Unclamped Inductive Waveforms



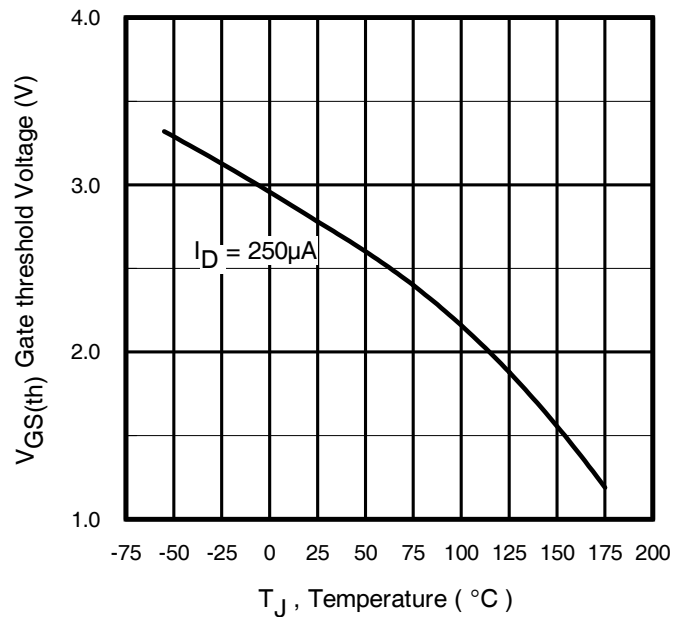
**Fig 13a.** Gate Charge Waveform



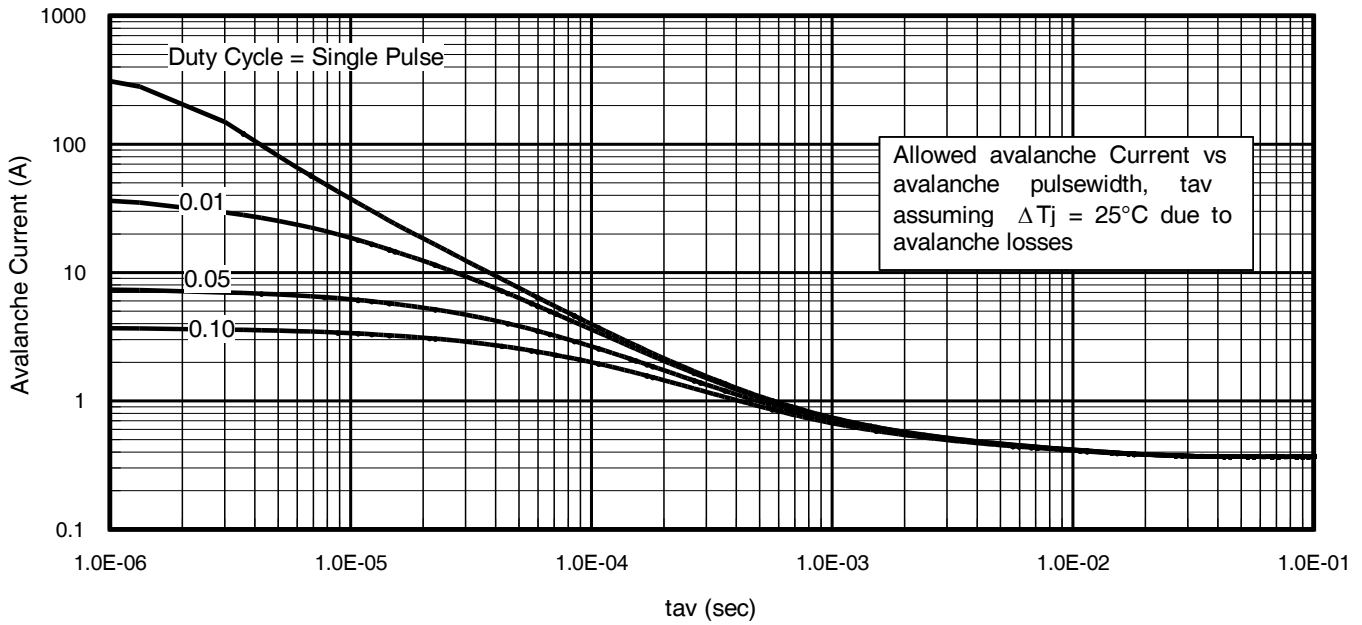
**Fig 13b.** Gate Charge Test Circuit



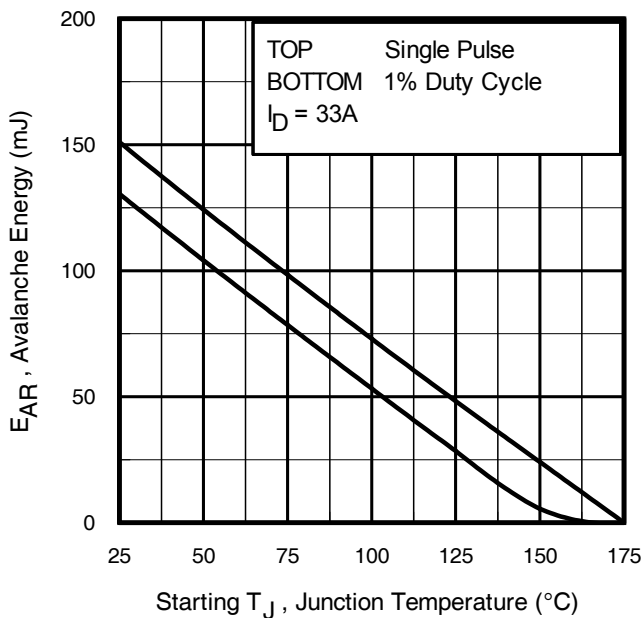
**Fig 12c.** Maximum Avalanche Energy vs. Drain Current



**Fig 14.** Threshold Voltage vs. Temperature



**Fig 15.** Typical Avalanche Current vs. Pulse width



**Fig 16.** Maximum Avalanche Energy vs. Temperature

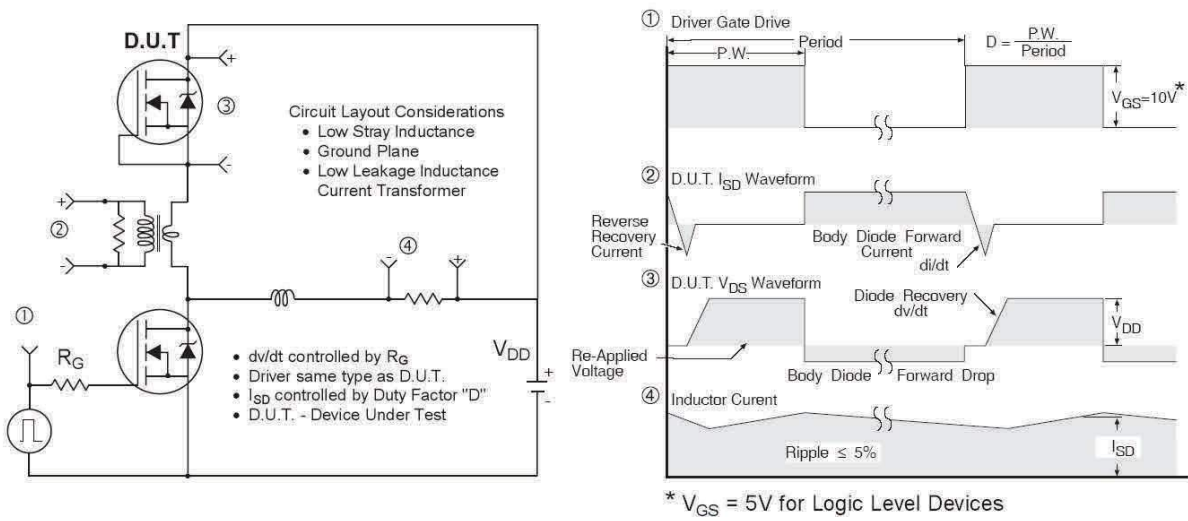
**Notes on Repetitive Avalanche Curves , Figures 15, 16: (For further info, see AN-1005 at [www.infineon.com](http://www.infineon.com))**

1. Avalanche failures assumption:  
Purely a thermal phenomenon and failure occurs at a temperature far in excess of  $T_{jmax}$ . This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as  $T_{jmax}$  is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
4.  $P_{D(ave)}$  = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6.  $I_{av}$  = Allowable avalanche current.
7.  $\Delta T$  = Allowable rise in junction temperature, not to exceed  $T_{jmax}$  (assumed as 25°C in Figure 15, 16).  
 $t_{av}$  = Average time in avalanche.  
 $D$  = Duty cycle in avalanche =  $t_{av} \cdot f$   
 $Z_{thJC}(D, t_{av})$  = Transient thermal resistance, see figure 11)

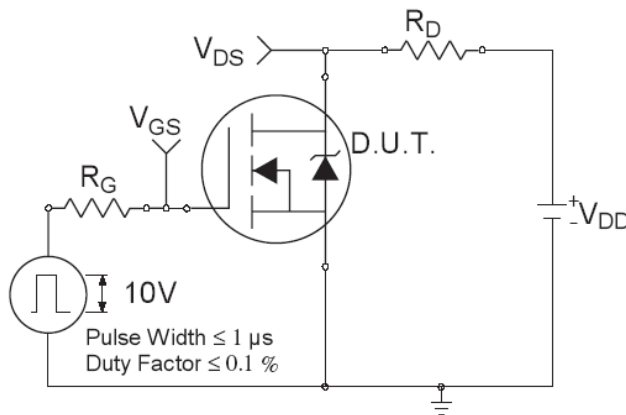
$$P_{D(ave)} = 1/2 ( 1.3 \cdot BV \cdot I_{av} ) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

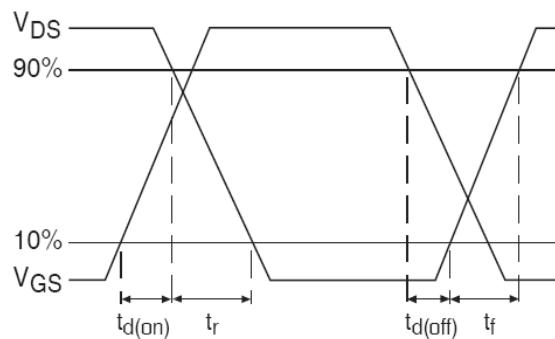
$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$



**Fig 17.** Peak Diode Recovery  $dv/dt$  Test Circuit for N-Channel HEXFET® Power MOSFETs



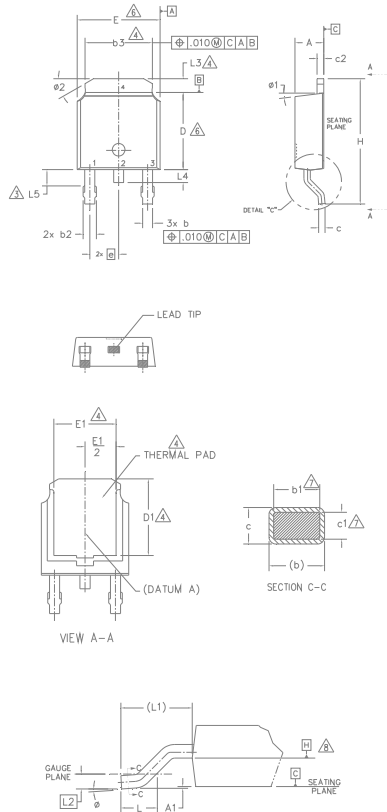
**Fig 18a.** Switching Time Test Circuit



**Fig 18b.** Switching Time Waveforms



## D-Pak (TO-252AA) Package Outline (Dimensions are shown in millimeters (inches))



- NOTES:
- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  - 2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]
  - △ LEAD DIMENSION UNCONTROLLED IN L5.
  - △ DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
  - 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
  - △ DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .006 [0.15] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
  - △ DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
  - △ DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
  - 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	2.18	2.39	.086	.094	7	
A1	-	0.13	-	.005		
b	0.64	0.89	.025	.035		
b1	0.64	0.79	.025	.031		
b2	0.76	1.14	.030	.045		
b3	4.95	5.46	.195	.215		4
c	0.46	0.61	.018	.024		7
c1	0.41	0.56	.016	.022		
c2	0.46	0.89	.018	.035		
D	5.97	6.22	.235	.245		6
D1	5.21	-	.205	-		4
E	6.35	6.73	.250	.265		6
E1	4.32	-	.170	-		4
e	2.29 BSC		.090 BSC			
H	9.40	10.41	.370	.410		
L	1.40	1.78	.055	.070		
L1	2.74 BSC		.108 REF.			
L2	0.51 BSC		.020 BSC			
L3	0.89	1.27	.035	.050	4	
L4	-	1.02	-	.040		
L5	1.14	1.52	.045	.060	3	
ϕ	0°	10°	0°	10°		
ϕ1	0°	15°	0°	15°		
ϕ2	25°	35°	25°	35°		

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT & CoPAK

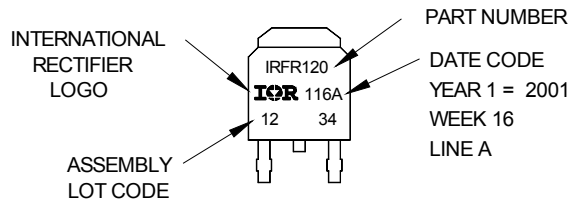
- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

## D-Pak (TO-252AA) Part Marking Information

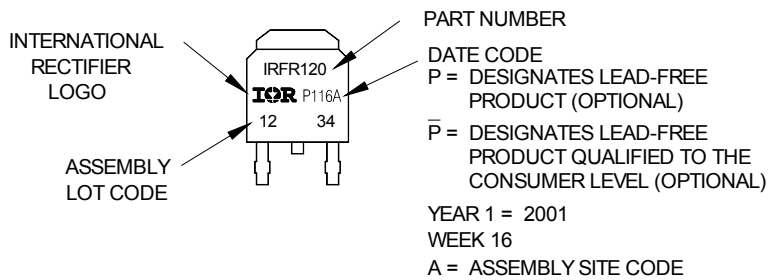
EXAMPLE: THIS IS AN IRFR120 WITH ASSEMBLY LOT CODE 1234 ASSEMBLED ON WW 16, 2001 IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates "Lead-Free"

"P̄" in assembly line position indicates "Lead-Free" qualification to the consumer-level



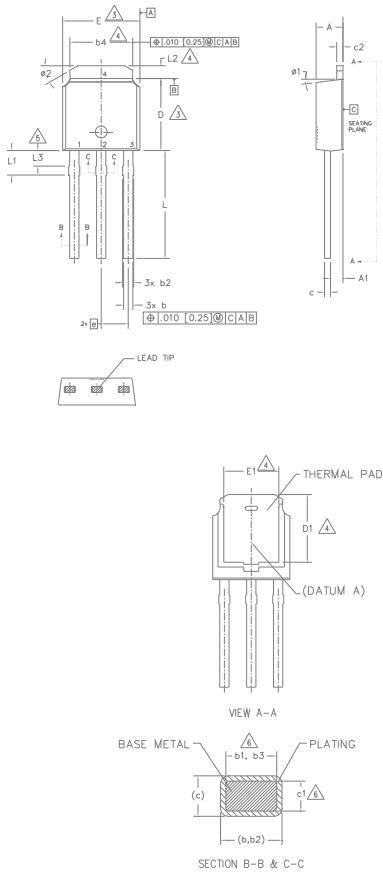
OR



### Notes:

1. For an Automotive Qualified version of this part please see <http://www.infineon.com/product-info/datasheets/data/aurfr3710z.pdf>
2. For the most current drawing please refer to Infineon website at <http://www.infineon.com/package/>

## I-Pak (TO-251AA) Package Outline Dimensions are shown in millimeters (inches)



- NOTES:
- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  - 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
  3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
  4. THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
  5. LEAD DIMENSION UNCONTROLLED IN L3.
  6. DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.
  - 7.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA (Date 06/02).
  - 8.- CONTROLLING DIMENSION : INCHES.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	0.89	1.14	.035	.045	
b	0.64	0.89	.025	.035	
b1	0.65	0.79	.025	.031	6
b2	0.76	1.14	.030	.045	
b3	0.76	1.04	.030	.041	6
b4	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	6
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	3
D1	5.21	-	.205	-	4
E	6.35	6.73	.250	.265	3
E1	4.32	-	.170	-	4
e	2.29 BSC		.090 BSC		
L	8.89	9.65	.350	.380	
L1	1.91	2.29	.045	.090	
L2	0.89	1.27	.035	.050	4
L3	0.89	1.52	.035	.060	5
ø1	0	15	0	15	
ø2	25	35	25	35	

### LEAD ASSIGNMENTS

### HEXFET

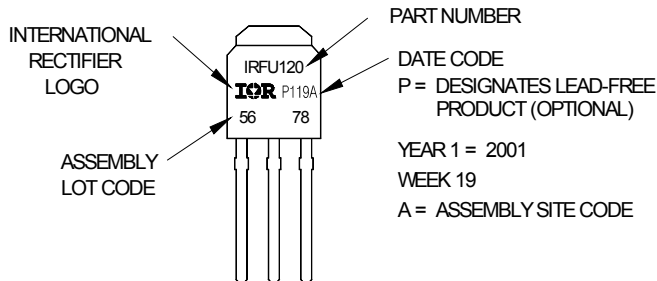
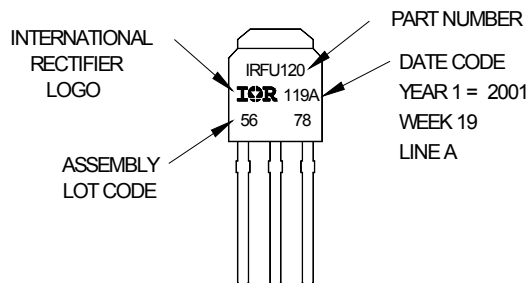
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

## I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120 WITH ASSEMBLY LOT CODE 5678 ASSEMBLED ON WW 19, 2001 IN THE ASSEMBLY LINE "A"

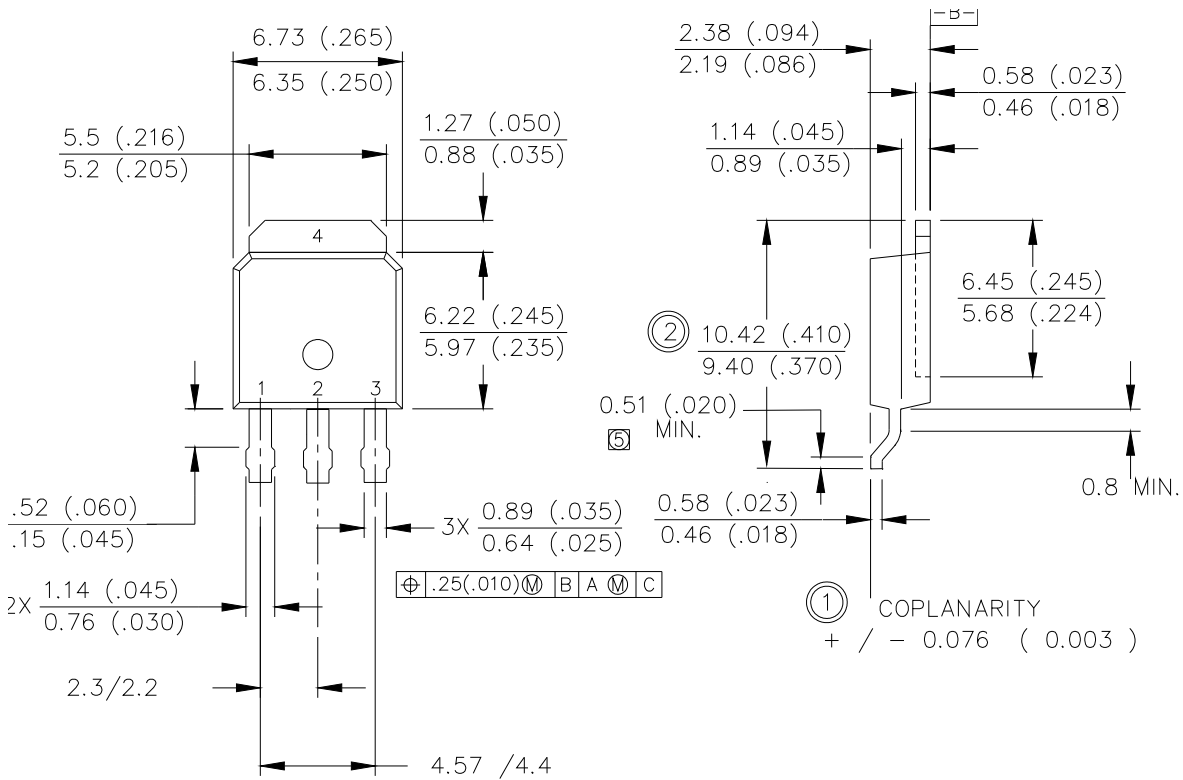
Note: "P" in assembly line position indicates Lead-Free

OR



### Notes:

1. For an Automotive Qualified version of this part please see <http://www.infineon.com/product-info/auto/>
2. For the most current drawing please refer to Infineon website at <http://www.infineon.com/package/>

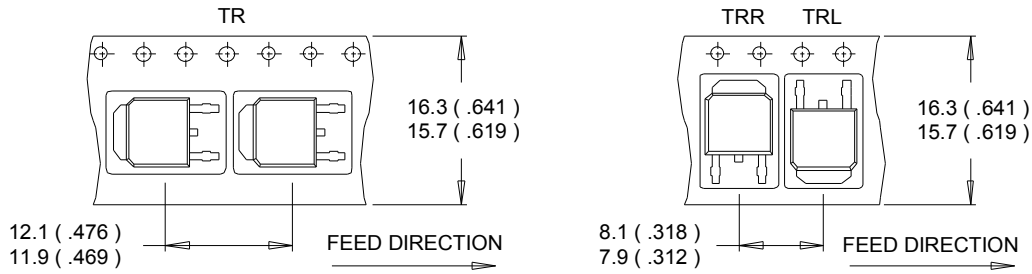
**I-Pak Leadform Option 701 Package Outline ®**  
 Dimensions are shown in millimeters (inches)


- 1-. GATE
- 2-. DRAIN
- 3-. SOURCE
- 4-. DRAIN

**NOTES:**

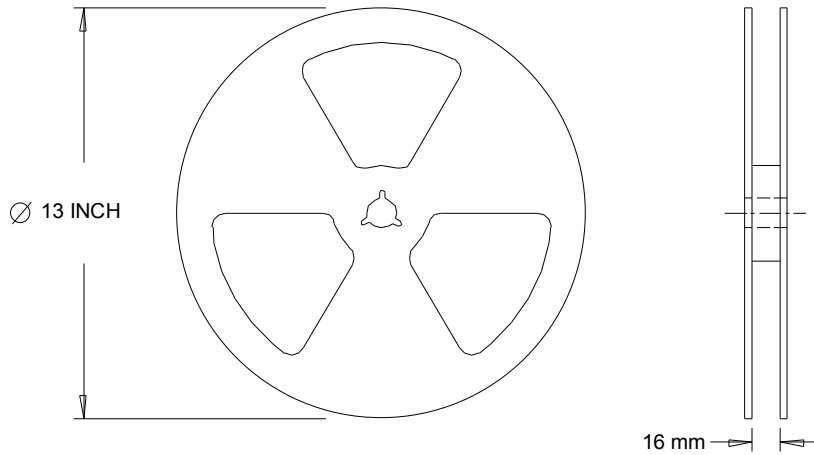
- 1.0 CONTROL DIMENSIONS IN INCHES
- 2.0 PARALLELISM AND ANGULARITY MAX. 0.076 (0.003)
- 3.0 LEADFORM CRITICAL DIMENSIONS DOUBLE RINGED

D-Pak (TO-252AA) Tape & Reel Information Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Note: For the most current drawing please refer to Infineon's web site [www.infineon.com](http://www.infineon.com)

## Qualification Information†

<b>Qualification Level</b>	Industrial (per JEDEC JESD47F) ††	
<b>Moisture Sensitivity Level</b>	D-Pak	MSL1  (per JEDEC J-STD-020D) ††
	I-Pak	
<b>RoHS Compliant</b>	Yes	

† Qualification standards can be found at Infineon’s web site [www.infineon.com](http://www.infineon.com)

†† Applicable version of JEDEC standard at the time of product release.

## Revision History

Date	Comments
5/31/2016	<ul style="list-style-type: none"> <li>Updated datasheet with corporate template.</li> <li>Added disclaimer on last page.</li> </ul>

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Trademarks updated November 2015

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**Document reference**

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